Claims Presented

- 1. (Original) A laser submount, comprising:
- a substrate;
- a lens above the substrate; and
- a laser above the substrate.
- (Original) The laser submount of claim 1, wherein the substrate is selected from the group consisting of silicon, quartz, sodium borosilicate glass, sapphire, gallium arsenide, silicon carbide, and gallium phosphide.
 - 3. (Currently Amended) The laser submount of claim 1, further comprising: a [planaraization]] planarization layer covering the lens; and an interconnect layer above the planarization layer.
- 4. (Original) The laser submount of claim 3, wherein the planarization layer is an oxide layer.
- 5. (Original) The laser submount of claim 3, further comprising: a dielectric layer above the interconnect layer; and a contact pad above the dielectric layer, wherein the laser is electrically connected to the contact pad.
- (Original) The laser submount of claim 5, further comprising:
 a sealing ring above the dielectric layer and surrounding the contact pad and the laser.
 - 7. (Original) The laser submount of claim 1, further comprising: at least one of a passive integrated circuit and an active integrated circuit.
 - 8-14. (Cancelled)